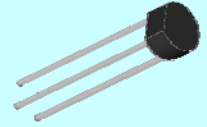


**MATERIAL COMPOSITION DECLARATION**

Supplier: Fagor Electrónica S. Coop

Package: Round Bridge



Part Number:

Description: Round Bridge Rectifier

COMPOSITION PART	MATERIAL NAME	MATERIAL MASS( mg)	MATERIAL MASS( %)	ELEMENT NAME COMPOSITION	CAS Nº	ELEMENT % ( BY WEIGHT)	Cd (ppm)	Pb (ppm)	Hg (ppm)	Cr 6+ (ppm)	PBBs (ppm)	PBDEs (ppm)
LEAD FRAME	Electrolitic Copper	750,016	63,32%	Cu Ag	7440-50-8 7440-22-4	99,9 0,1	< 2	< 2	< 2	< 2	< 5	< 5
ENCAPSULATION	Capsule	109,948	9,28%	Phenol formaldehido		100	≤70	≤700	≤700	≤700	≤300	≤300
	Epoxy Resin & Hardener	303,148	25,59%	bis-(epoxiciclohexil)-metilcarboxilato	2386-87-0	20,0-28,0	< 2	< 2	< 2	< 2	< 5	< 5
				Epoxy resin of bisfenol-A- epiclorhidrina	25068-38-6	10,0-18,0						
				SiO2 (Fused Silica)	60676-860	15,0-43,0						
				anhidrido metil-tetrahidroftálico	26590-20-5	27,0-39,0						
CHIP	Doped Silicon Glass Passivated	3,138	0,26%	Si Ni SiO2 PbO2 Al2O3	7440-21-3 7440-02-0 7631-86-9 1309-60-0 1344-28-1	77,9-79,2 0,8-1,2 9,4-9,8 8,8-9,2 0,8-1,2	< 2	45148 (**)	< 2	< 2	< 5	< 5
SOLDER PASTE	Pb/Sn5 Solder Paste	5,120	0,43%	Pb Sn Sb	7439-92-1 7440-31-5 7440-36-0	92,8 - 95,0 4,5 - 5,5 0,2	< 2	940000 (*)	< 2	< 2	< 5	< 5
COATING	Silver 100%	13,150	1,11%	Ag	7440-22-4	99,9	< 2	< 2	< 2	< 2	< 5	< 5
WHOLE ITEM		<b>1.184,520</b>	100,00%									

**Exception according to annex of Directive 2002/95/EC (RoHS):**

\* Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85% lead)

\*\* Lead in glass of cathode ray tubes, electronic componentes and fluorescent tubes